

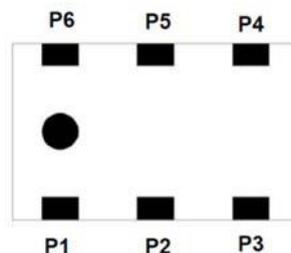
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

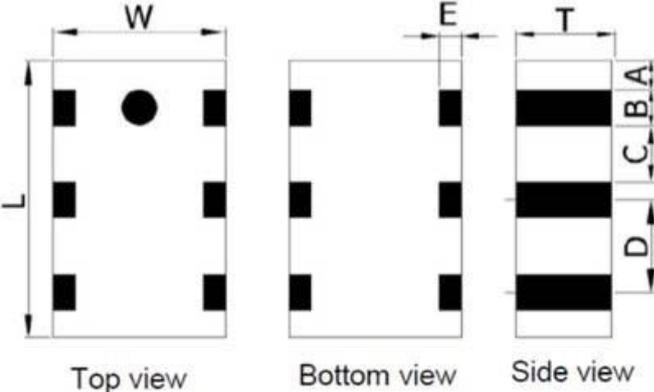
NO.	Parameter	SPC
1	Frequency range (f1)	2400~2500 MHz
		4900~6000 MHz
	Frequency range (f2)	1570~1610 MHz
2	Insertion Loss (f1)	0.8 dB max. @ 2400~2500 MHz
		0.6 dB max. @ 4900~6000 MHz
	Insertion Loss (f2)	0.7 dB max. @ 1570~1610 MHz
3	Attenuation (f1)	20 dB min. @ 1570~1610 MHz
		15 dB min. @ 2400~2500 MHz
	Attenuation (f2)	15 dB min. @ 4900~6000 MHz
4	VSWR (In BW)	2.0 max.
5	Port Impedance	50Ω
6	Power	2.0 W max.
7	Operation Temperature Range	-40°C ~ +85°C

Construction

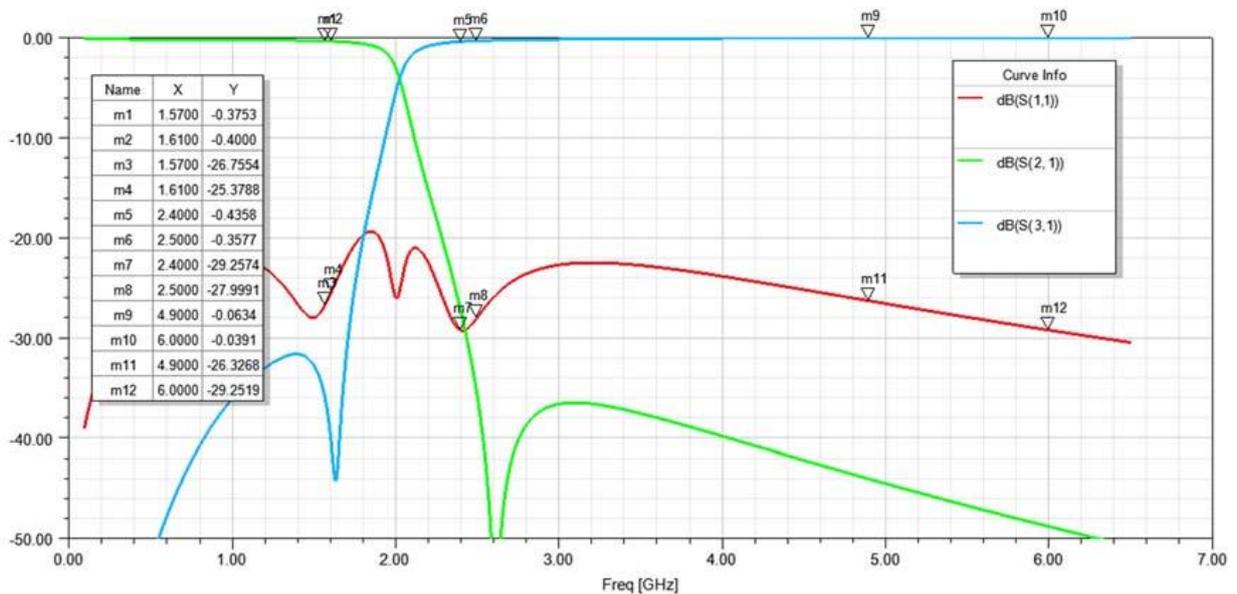


PIN	Connection	PIN	Connection
P1	GND	P4	Low Port
P2	Antenna Input	P5	GND
P3	GND	P6	Higher Port

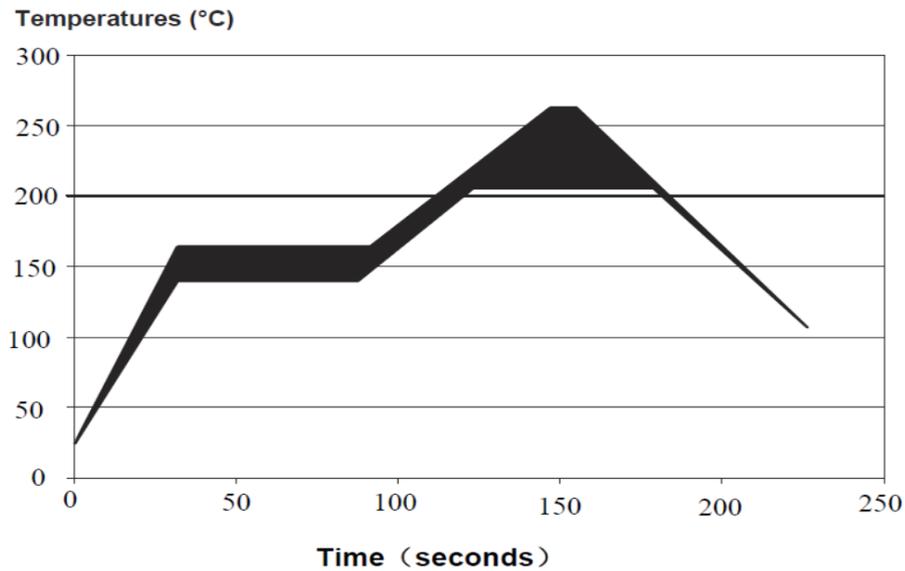
Dimensions

Figure	Symbol	Dimension (mm)
 <p>Top view Bottom view Side view</p>	L	1.6 ± 0.10
	W	0.8 ± 0.10
	T	0.6 ± 0.10
	A	0.2 ± 0.10
	B	0.2 ± 0.10
	C	0.3 ± 0.10
	D	0.5 ± 0.10
E	0.15 ± 0.10	

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.